

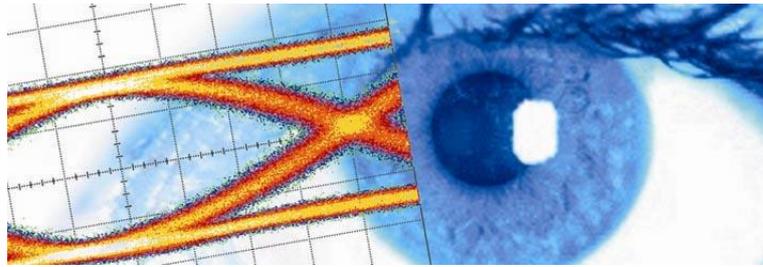


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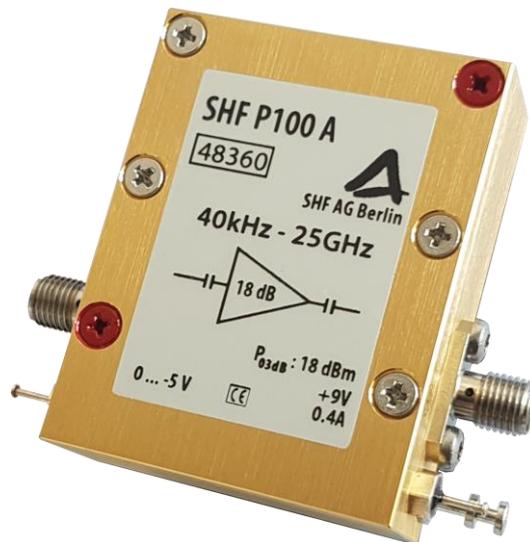
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Datasheet

SHF P100 A

Broadband Amplifier





Description

The SHF P100 A broadband amplifier is the RoHS compliant successor of the popular SHF 100 AP. The SHF P100 A is a two stage, wideband RF amplifier featuring flat gain and low group delay variation. By use of proprietary monolithic microwave integrated circuits (MMICs) a 1 dB compression point of 13 dBm and low noise figure are achieved. An internal voltage regulation protects the amplifier against accidental reverse voltage connection and makes it robust against line voltage ripple. In addition the amplifier is characterized by a gain control input for up to 3 dB gain reduction.

Applications

- Optical Communications, Modulator Driver
- High-Speed Pulse Experiments
- Satellite Communications
- Research and Development
- Antenna Measurements
- RF over fiber

Available Options

01: DC return on input (max. ± 1.75 V, max. 35 mA)¹

02: Built-in bias tee on input (max. ± 12 V, max. 200 mA)¹

03: DC return on output (max. ± 1.75 V, max. 35 mA)¹

04: Built-in bias tee on output (max. ± 12 V, max. 200 mA)¹

MP: Matches the phase of two amplifiers

¹ The options 01 & 02 or 03 & 04 cannot be combined.

If an option is chosen, the maximum gain and the maximum output power might be reduced by up to 1 dB. The low frequency 3 dB Point might be increased up to 60 kHz.



Specifications - SHF P100 A

Parameter	Unit	Symbol	Min.	Typ.	Max.	Comment
Absolute Max Ratings						
Maximum RF Input	dBm V	$P_{in\ max}$			10 2	peak to peak voltage
DC Voltage at RF Input	V				± 12	AC coupled input
DC Voltage at RF Output	V				± 12	AC coupled output
Positive Supply Voltage	V		8.5	9	12	reverse voltage protected
Positive Supply Current	A	I_{DD}		0.4	0.5	
Gain Control Voltage	V	U_{GC}	-5		0	Reduction by approx. 3dB $I_{GC} \leq 10\ mA$ pin open: max gain is achieved.
Case Temperature ²	T_{case}	$^{\circ}C$	10	45	50	

² If operated with heat sink (part of the delivery) at room temperature there is no need for additional cooling.



Parameter	Unit	Symbol	Min.	Typ.	Max.	Comment
Electrical Characteristics (At 45°C case temperature, unless otherwise specified)						
High frequency 3 dB point	GHz	f _{HIGH}	25			
Low frequency 3 dB point	kHz	f _{LOW}		30	40	
Gain	dB	S ₂₁	17	18		non-inverting
Output Power at 1 dB Compression	dBm V	P _{01dB}	13 2.8			10 MHz...17 GHz peak to peak voltage
Output Power at 2 dB Compression	dBm V	P _{02dB}	16 4.0			10 MHz...17 GHz peak to peak voltage
Output Power at 3 dB Compression	dBm V	P _{03dB}	17.5 4.7			10 MHz...17 GHz peak to peak voltage
Input Return Loss	dB	S ₁₁		-12	-10	< 20 GHz
Output Return Loss	dB	S ₂₂		-10	-9	< 20 GHz
Rise Time/Fall Time	ps	t _r /t _f			17 20	V _{out} ~ 4.5 V, 20 Gbps, 20%...80% Deconvoluted ^{3,4} Full Setup ³
Jitter	ps	J _{RMS}			0.9 1.0	V _{out} ~4.5 V, 20 Gbps Deconvoluted ^{3,4} Full Setup ³
Group Delay Ripple	ps				±50	2...20 GHz, 100 MHz aperture
Power Consumption	W			3.6		9 V supply voltage
Mechanical Characteristics						
Input Connector						SMA female
Output Connector						SMA female
Dimensions	mm					51x40x16 excluding connectors

³ Measured with the following setup: SHF 40A BPG -> DUT (SHF P100 A) -> Agilent 86100C with 50 GHz sampling head and precision time base.

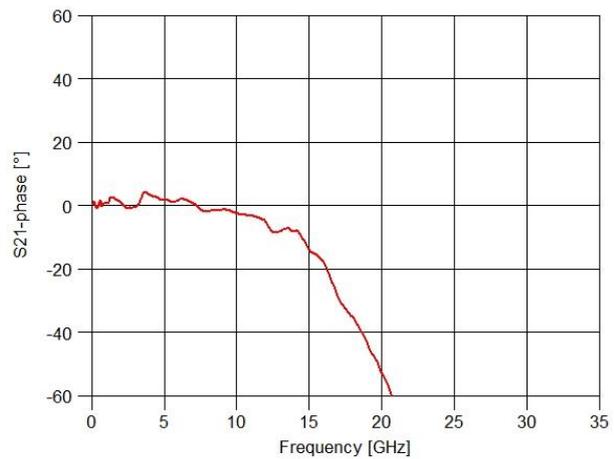
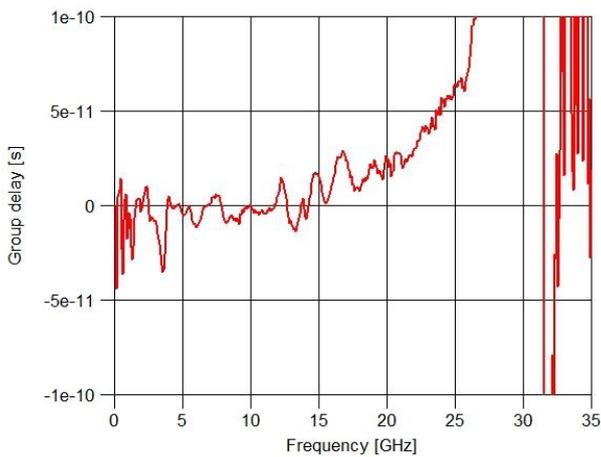
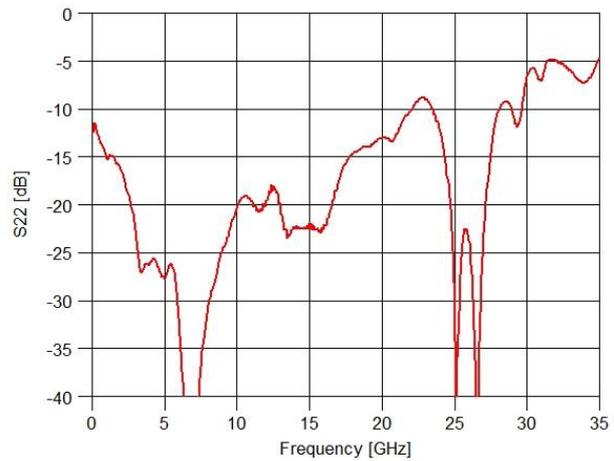
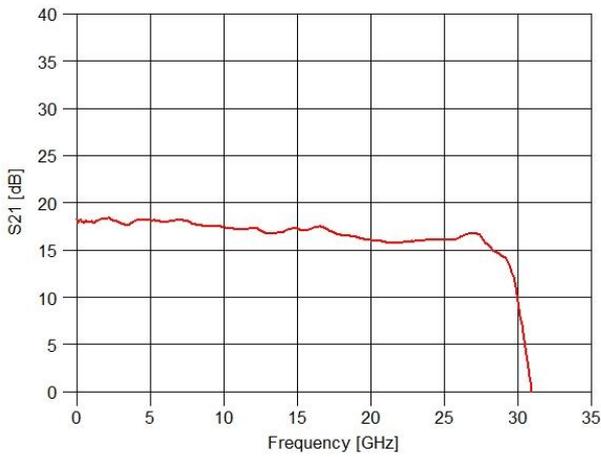
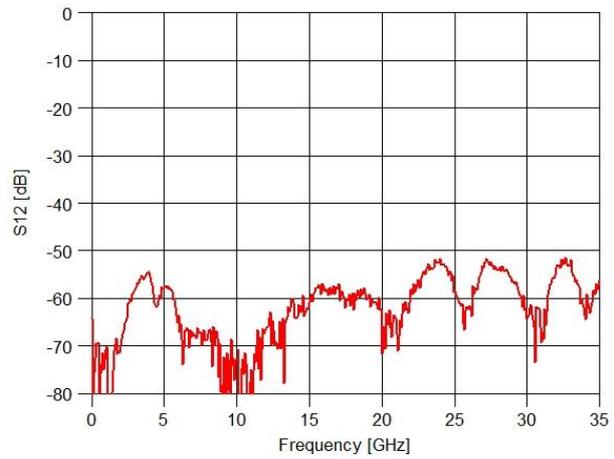
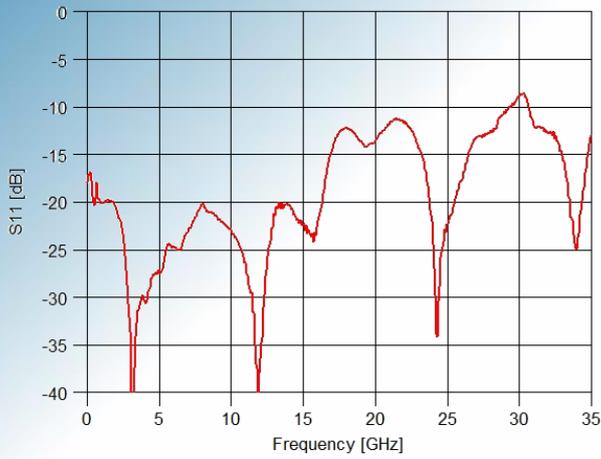
⁴ Calculation based on typical results of setup without DUT :

$$t_r/t_f \text{ deconvoluted} = \sqrt{(t_r/t_f \text{ full setup})^2 - (t_r/t_f \text{ setup w/o DUT})^2} = \sqrt{(t_r/t_f \text{ full setup})^2 - 12 \text{ ps}^2}$$

$$J_{RMS} \text{ deconvoluted} = \sqrt{(J_{RMS} \text{ full setup})^2 - (J_{RMS} \text{ setup w/o DUT})^2} = \sqrt{(J_{RMS} \text{ full setup})^2 - 350 \text{ fs}^2}$$



Typical S-Parameters, Group Delay and Phase Response

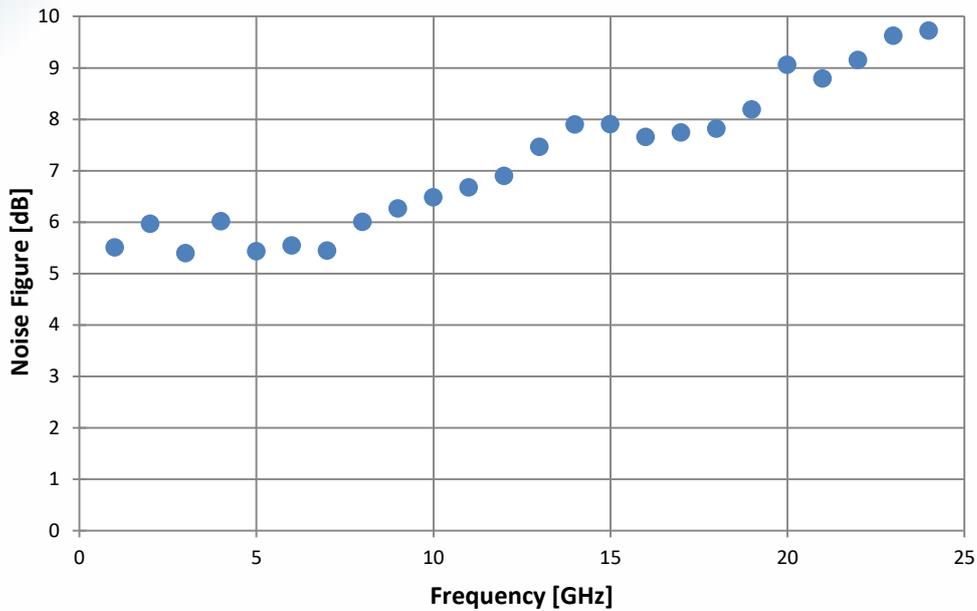


Aperture of group delay measurement: 100 MHz



Typical Noise Figure

The measurement had been performed using a FSW85 Spectrum Analyzer by Rhode & Schwarz. The noise figure defines the degradation of the signal-to-noise ratio when the signal passes the amplifier. An ideal amplifier would amplify the noise at its input along with the signal. However, a real amplifier adds some extra noise from its own components and degrades the signal-to-noise ratio. Please note that this applies to small signals only. When the amplifier is used close to or in its saturation region additional non-linear effects will impact the signal-to-noise ratio and the signal waveform.

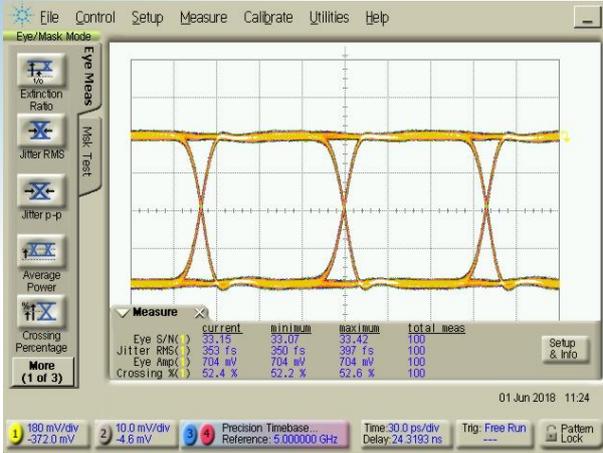




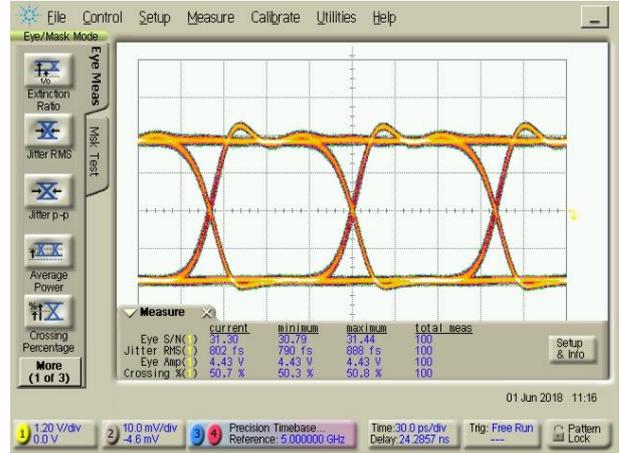
Typical Binary Waveforms

Measurements at 10, 20 and 28 Gbps (PRBS 2³¹-1) had been performed using a SHF BPG 40 A and an Agilent 86100C DCA with Precision Time Base Module (86107A) and 50 GHz Sampling Head (83484A).

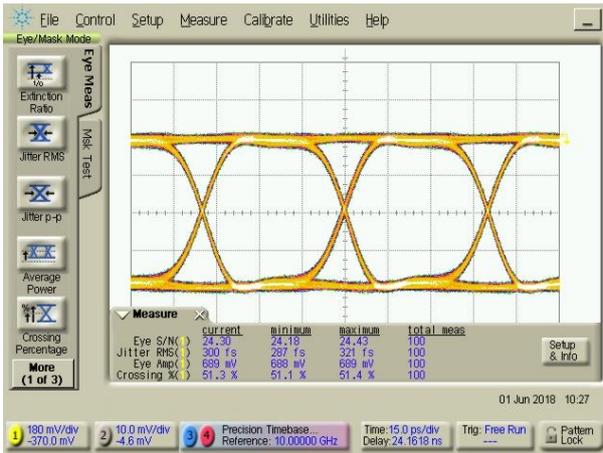
The measurements will be part of the inspection report delivered with each particular device.



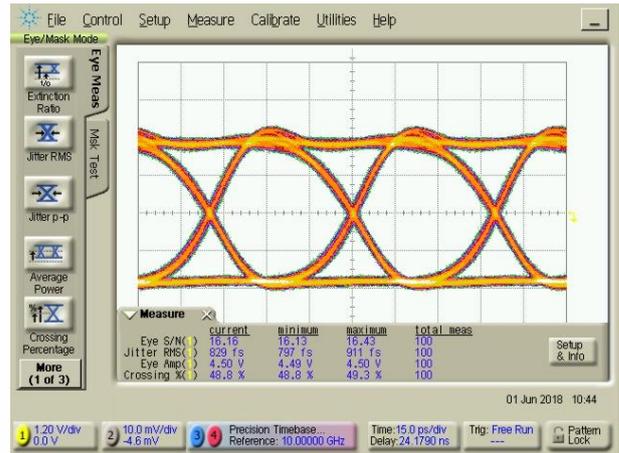
Input Signal @ 10 Gbps



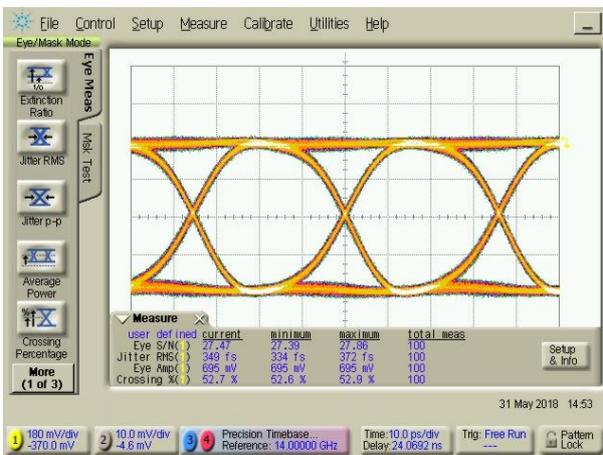
Output Signal @ 10 Gbps



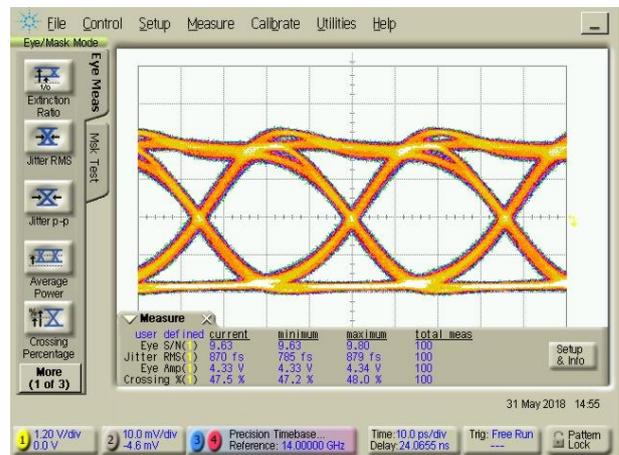
Input Signal @ 20 Gbps



Output Signal @ 20 Gbps



Input Signal @ 28 Gbps



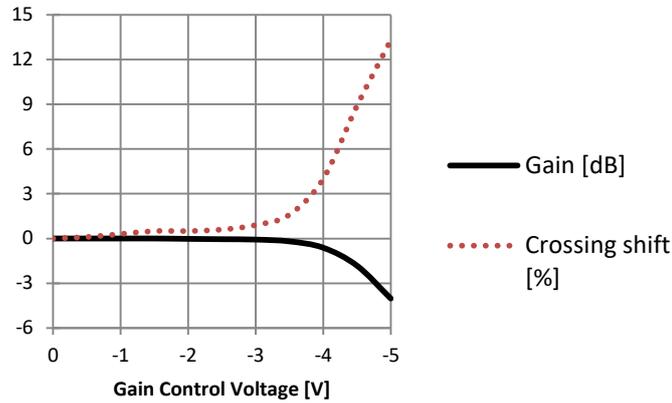
Output Signal @ 28 Gbps



Handling Instructions

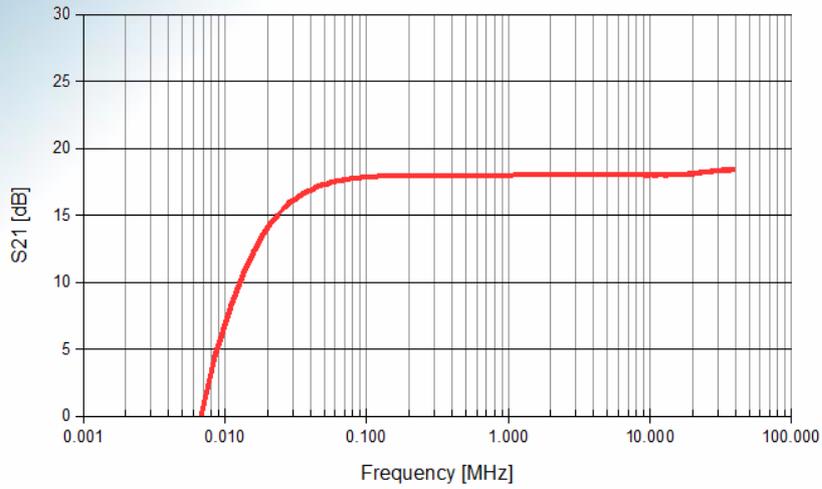
To operate the amplifier a positive supply voltage of approximately +9 V must be applied.

The gain can be adjusted by applying a voltage of 0 to -5 V. If this pin is left open, the amplifier will have maximum gain. By reducing the gain the crossing will shift. Typical characteristics are shown in the following diagram for an input voltage of 0.5 V with 50% crossing.

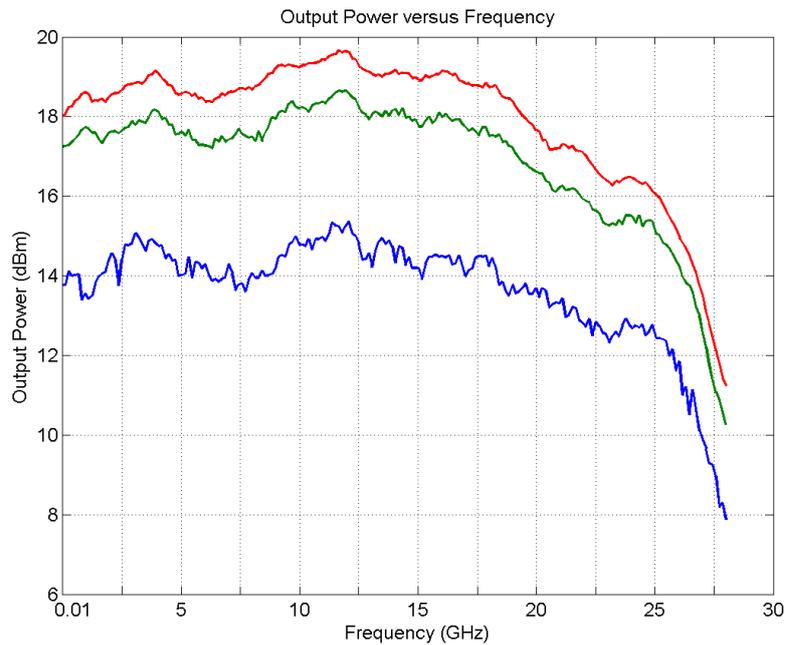




Typical Low Frequency Response



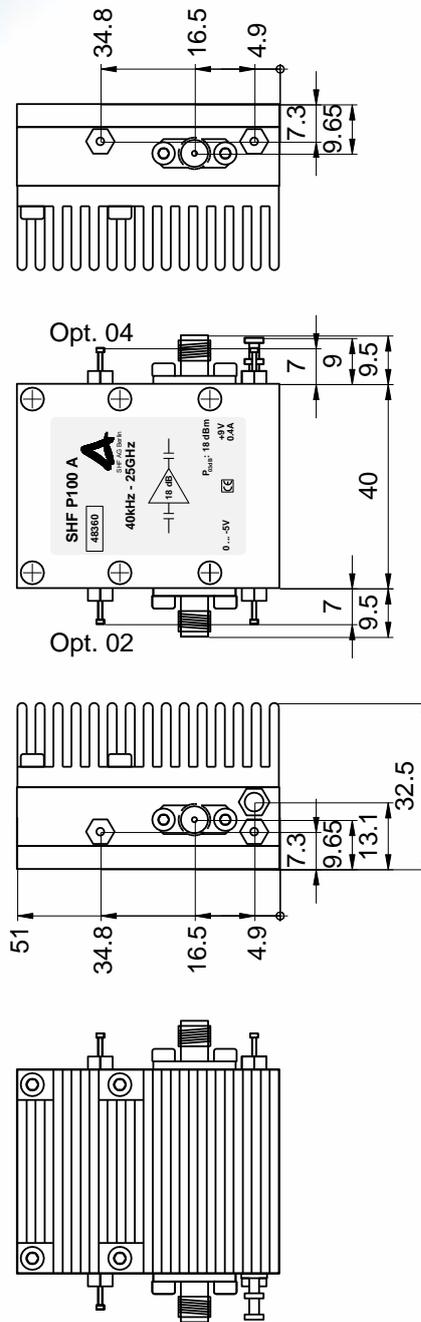
Typical Saturation power



Top (red): 3 dB compression;
Middle (green): 2 dB compression;
Bottom (blue): 1 dB compression



Mechanical Drawing with Heat Sink

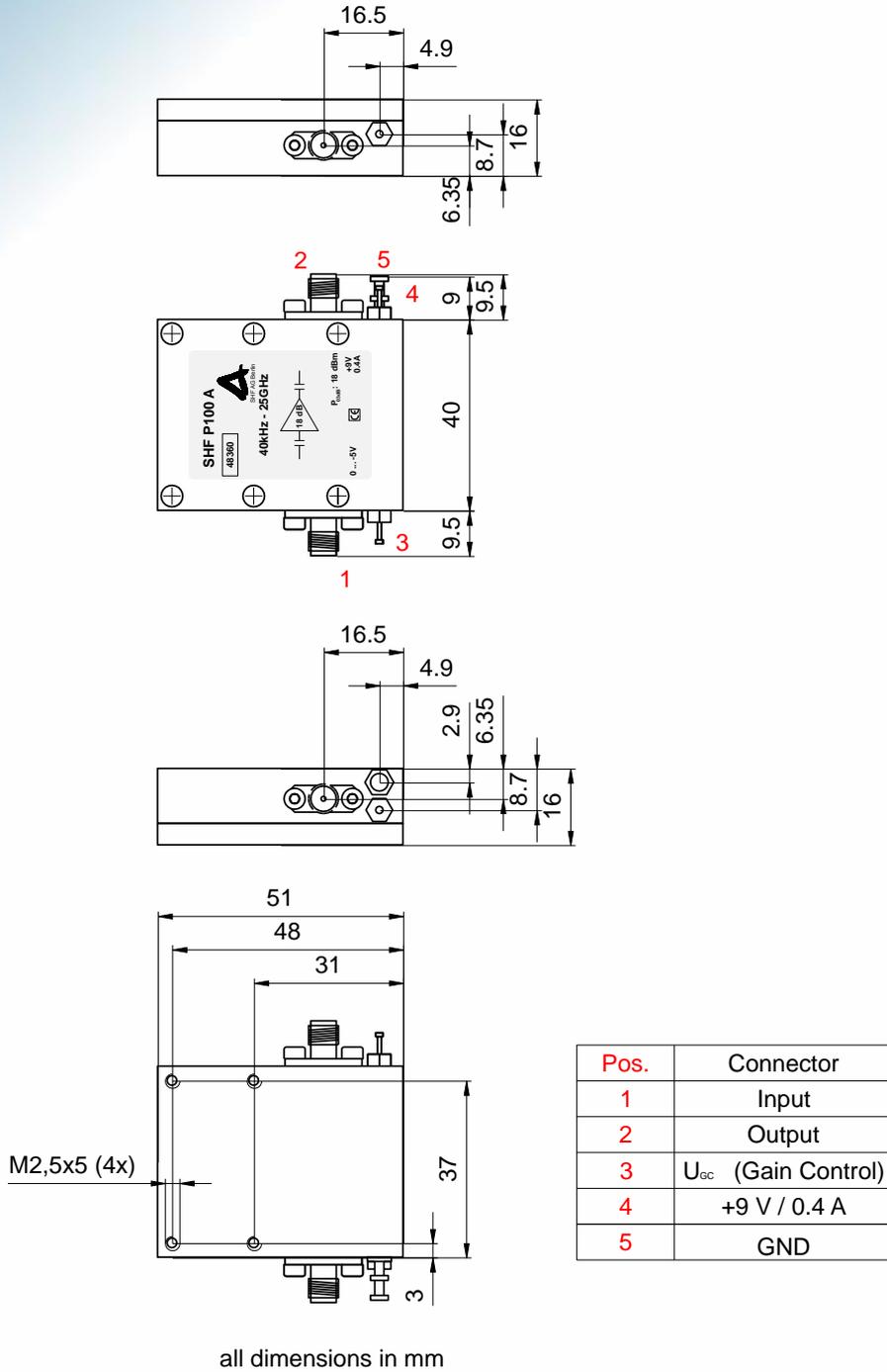


all dimensions in mm

For permanent mounting remove the heat sink from the amplifier. In that case please ensure that adequate cooling of the amplifier is guaranteed. It is recommended to use thermal paste or a thermal gap pad for the mounting. In order to separate the heat sink from the amplifier, remove the four screws on the heat sink. Please note, thermal paste is used between the heat sink and the amplifier housing.



Mechanical Drawing without Heat Sink



Please ensure that adequate cooling of the amplifier is guaranteed.



User Instructions

ATTENTION!

Electrostatic sensitive GaAs FET amplifier

1. To prevent damage through static charge build up, cables should be always discharged before connecting them to the amplifier!
2. Attach a 50 Ohm output load **before** supplying DC power to the amplifier!
3. The supply voltage can be taken from any regular power supply and can be connected to the supply feed-through filter via an ON / OFF switch.
4. It make sense to use the minimum supply voltage. A higher one increases the power dissipation of the internal voltage stabilizer.
5. Using a 3 dB or 6 dB input attenuator will result in a 6 dB or 12 dB increase of the input return loss. For minimal degradation of amplifier rise time, these attenuators should have a bandwidth specification of more than the amplifier bandwidth.
6. High input voltages will drive the amplifier's output stage into saturation, leading to waveform peak clipping.
7. Saturated output voltages can only be used without damage while the amplifier is connected to a 50 Ohm precision load with a VSWR of less than 1.2 or better than 20 dB return loss.
8. While using a reflective load the output voltage has to be reduced to a safe operating level according to the magnitudes of the reflections.

ATTENTION: At radio frequencies a capacitive load can be transformed to an inductive one through transmission lines! With an output stage driven into saturation this may lead to the immediate destruction of the amplifier (within a few ps)!

9. For the DC-connections flexible cable $0.2...0.5 \text{ mm}^2$ / AWG 24...20 are recommended. A maximum soldering temperature of 260 °C for 3 seconds is recommended for the feedthrough (positive supply voltage and bias tees pin). The ground pin requires significantly more heat as it is connected to the solid housing.